

Material Data Sheet

Varistor

Product Class: Disk Varistor Q* B722xxQ*V87 Date 30.09.2019 IMDS ID if available Version: 5.06

| Product Part (IMDS: semi component) | Material Class (IMDS: Material) | Material (Classification) VDA 231 | Substance | TMPS**) [wt%] | CAS if applicable | typical mass of material [wt-%] | Traces see 1) |
|---|------------------------------------|---|---|-----------------------------------|---|---------------------------------------|------------------|
| Active Part | Ceramic | 3B | ZnO Bi2O3 Sb2O3 Co3O4 NiO others*) | 91 4,0 2,5 1 0,5 1 | 1314-13-2 1304-76-3 1309-64-4 1308-06-1 1313-99-1 | 45 | |
| Termination | Composite | 4D | Cu or Ag Glass frit (boro-silicate) | 95 5 | 7440-50-8 7440-22-4 | 0,5 | |
| Solder | Heavy Metal | 1C8 | Sn Ag Cu | 96,5 3 0,5 | 7440-31-5 7440-22-4 7440-50-8 | 4,5 | |
| Leads | Heavy Metal | 1A | Fe | 100 | 7439-89-6 | 27,5 | |
| | Heavy Metal | 1C12 | Cu | 100 | 7440-50-8 | 4,9 | |
| | Heavy Metal | 1C8 | Sn | 100 | 7440-31-5 | 1,6 | |
| Encapsulation | Duromer | 2D Halogen-free coating | SiO2 Epoxy Pyromellitic dianhydride Phosphated epoxy others*) | 46 40 6,5 5 2,5 | 60676-86-0 25036-25-3 89-32-7 | 16 | |
| | 100 | | | | | | |

| sizes [mm] | weight range [g] | material numbers | sizes [mm] | weigl | ht ran | ige [g] | material numbers | | |
|--|--------------------------------|-----------------------------|-----------------------|-----------|---|--|---|--|--|
| 17 | 2.4 – 4.5 | B72214Q*V87 | 23 | 4.1 - 8.0 | | | B72220Q*V87 | | |
| Not part of a | Product Class | | | | | | | | |
| Contact | act Mr. Christoph Ronner | | | | | Important remarks: | | | |
| Division | PPD Q QM | | | | 1) | | aration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are | | |
| Address | 8530 Deutschlandsberg, AUSTRIA | | | | product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. | | | | |
| | Tel: +43 3462 800 2139 | mailto: functional.ppd-eqpn | n.db@tdk-electronics. | tdk.com | 2) | This Material Data Sheet contains typical values of the respective products set f | | | |
| *) others: .(not declarable or prohibited substances acc. GADSL) | | | | | | herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements | | | |
| **) typical mass percentage of substance | | | | | | g product specifications, unless otherwise explicitly agreed in writing. TDK | | | |
| | | | | | | | ONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY | | |
| | | | | | | | SENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR ORY. WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED | | |
| | | | | | | | , INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR | | |
| | | | | | | WARRA | NTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE | | |

WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.
The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions)
of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment. RoHS - Exemptions for the Product Class / Product according to Annex III: (🗹 valid 🗆 not valid)

| ☑ no exemptions; | | | | | | |
|----------------------|---|--|--|--|--|--|
| Exemption 6 (a): | Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight; | | | | | |
| Exemption 6 (b): | Lead as an alloying element in aluminium containing up to 0,4 % lead by weight; | | | | | |
| Exemption 6 (c): | Copper alloy containing up to 4 % lead by weight; | | | | | |
| Exemption 7 (a): | Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead); | | | | | |
| Exemption 7 (c)-I: | Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound; | | | | | |
| Exemption 7 (c)-II: | Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher; | | | | | |
| Exemption 7 (c)-III: | Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC; | | | | | |
| Exemption 15: | Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages; | | | | | |
| Other Exemption the | ian above | | | | | |